### 503077127 11/26/2014

## PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
WEI-TSUNG CHEN	11/21/2014
CHUANG-CHUANG TSAI	11/21/2014
TED-HONG SHINN	11/21/2014
XUE-HUNG TSAI	11/21/2014
CHIH-HSIANG YANG	11/21/2014

#### **RECEIVING PARTY DATA**

Name:	E INK HOLDINGS INC.	
Street Address:	NO. 3, LI-HSIN RD.1, SCIENCE-BASED INDUSTRIAL PARK,	
City:	HSINCHU	
State/Country:	TAIWAN	

#### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	14552464

#### **CORRESPONDENCE DATA**

**Fax Number:** (510)580-7280

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Email: usa@jcipgroup.com.tw

Correspondent Name: JIANQ CHYUN INTELLECTUAL PROPERTY OFFICE

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Address Line 4: TAIPEI, TAIWAN

ATTORNEY DOCKET NUMBER:	50235-US-PA
NAME OF SUBMITTER:	BELINDA LEE
SIGNATURE:	/Belinda Lee/
DATE SIGNED:	11/26/2014

**Total Attachments: 2** 

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PATENT 503077127 REEL: 034266 FRAME: 0522

## **ASSIGNMENT**

#### WHEREAS,

- 1. Wei-Tsung Chen
- 3. Ted-Hong Shinn
- 5. Chih-Hsiang Yang

- 2. Chuang-Chuang Tsai
- 4. Xue-Hung Tsai

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: SEMICONDUCTOR STRUCTURE

ſ	1	Filed:	Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, E Ink Holdings Inc.

of No. 3, Li-Hsin Rd.1, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

PATENT REEL: 034266 FRAME: 0523

# ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Wei - Twee Chen	Date: Nov. 21, 2014			
Sole or First Joint Inventor: Wei-Tsung Chen				
Signature: Chuang Chuang Tsai	Date: Nov. 21, 2014			
Second Joint Inventor (if any): Chuang-Chuang Tsai				
Signature: Ted Hong Shinn Third Joint Inventor (if any): Ted-Hong Shinn	Date: Nov. 21, 2014			
Signature: Yue - Hung 754; Fourth Joint Inventor (if any): Xue-Hung Tsai	Date: Nov. 21, 2014			
Signature: Chih Hs ang Yang Fifth Joint Inventor (if any): Chih-Hsiang Yang	Date: Nov. 21, 2014			